

# SOT686-1

plastic low profile fine-pitch ball grid array package; 64 balls;  
body 6 x 6 x 1.05 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	LFPGA64
<b>Package type industry code</b>	LFPGA64
<b>Package style descriptive code</b>	LFPGA (low profile fine-pitch ball grid array)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	11-3-2002

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	5.9	-	6	6.1	mm
E	package width	5.9	-	6	6.1	mm
A	seated height	[tbd]	-	1.5	1.5	mm
A <sub>2</sub>	package height	0.95	-	1.05	1.2	mm
n <sub>2</sub>	actual quantity of termination	-	-	64	-	



## 2. Package outline

LFBGA64: plastic low profile fine-pitch ball grid array package; 64 balls; body 6 x 6 x 1.05 mm SOT686-1

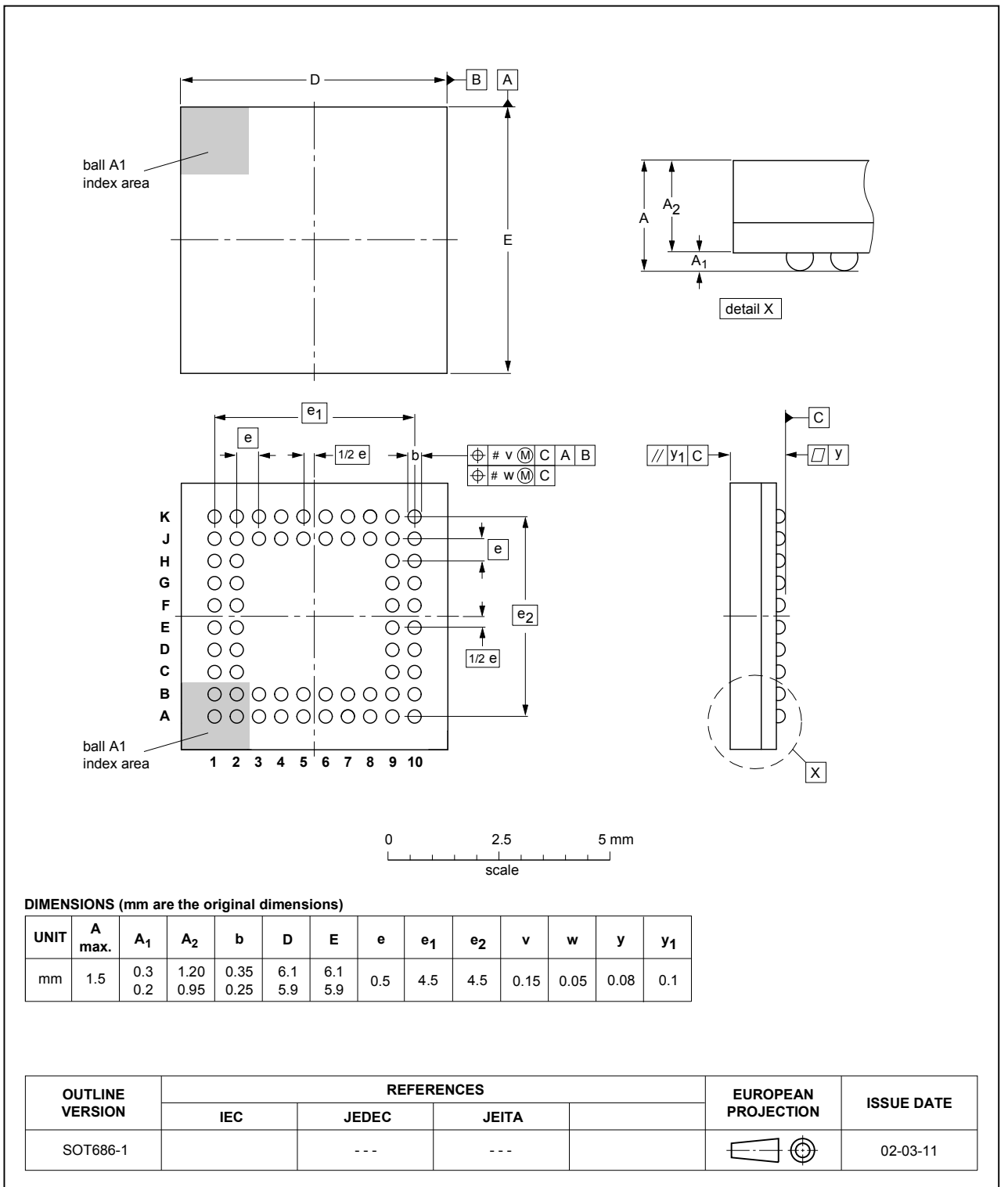


Fig. 1. Package outline LFBGA64 (SOT686-1)

### 3. Soldering

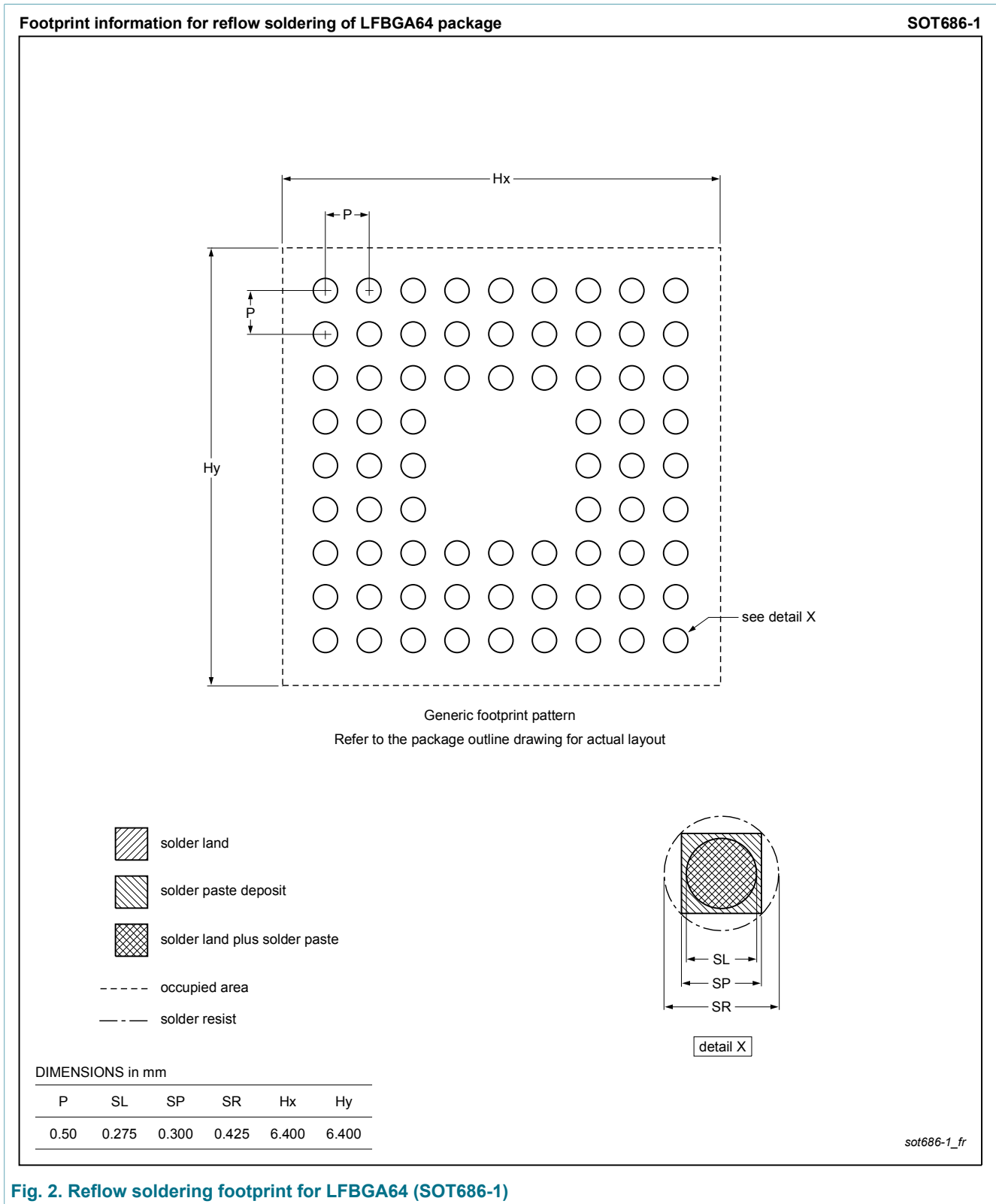


Fig. 2. Reflow soldering footprint for LFBGA64 (SOT686-1)

## 4. Legal information

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